SCDS214 - OCTOBER 2005

Description

The TS5A3359 is a single-pole triple-throw (SP3T) analog switch that is designed to operate from 1.65 V to 5.5 V. The device offers a low ON-state resistance and excellent ON-state resistance matching with the break-before-make feature, to prevent signal distortion during the transferring of a signal from one channel to another. The device has an excellent total harmonic distortion (THD) performance and consumes very low power. These features make this device suitable for portable audio applications.

Applications

- Cell Phones
- PDAs
- Portable Instrumentation
- Audio and Video Signal Routing
- Low-Voltage Data Acquisition Systems
- Communication Circuits
- Modems

(3)

(2)

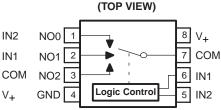
NO₂

- Hard Drives
- Computer Peripherals
- Wireless Terminals and Peripherals

YEP OR YZP PACKAGE (BOTTOM VIEW) GND 4 Logic Control 5 IN2 NO0 1 8

(6)

(8)



FUNCTION TABLE

IN2	IN1	COM TO NO, NO TO COM
L	L	OFF
L	Н	COM = NO0
Н	L	COM = NO1
Н	Н	COM = NO2

Features

- Isolation in the Power-Down Mode, V₊ = 0
- Specified Break-Before-Make Switching
- Low ON-State Resistance (1 Ω)
- Control Inputs Are 5.5-V Tolerant
- Low Charge Injection
- Excellent ON-State Resistance Matching
- Low Total Harmonic Distortion (THD)
- 1.65-V to 5.5-V Single-Supply Operation
- Latch-Up Performance Exceeds 100 mA Per JESD 78. Class II
- ESD Performance Tested Per JESD 22
 - 2000-V Human-Body Model (A114-B, Class II)
 - 1000-V Charged-Device Model (C101)

Summary of Characteristics

 $V_1 = 5 \text{ V. } T_{\Lambda} = 25^{\circ}\text{C}$

V ₊ - 3 V, I _A - 23 C	
Configuration	Triple 3:1 Multiplexer/ Demultiplexer (1 × SP3T)
Number of channels	1
ON-state resistance (ron)	1.1 Ω
ON-state resistance match (Δr _{ON})	0.1 Ω
ON-state resistance flatness (ron(flat))	0.15 Ω
Turn-on/turn-off time (t _{ON} /t _{OFF})	40 ns/35 ns
Break-before-make time (t _{BBM})	1 ns
Charge injection (Q _C)	40 pC
Bandwidth (BW)	100 MHz
OFF isolation (OISO)	-65 dB at 1 MHz
Crosstalk (XTALK)	-66 dB at 1 MHz
Total harmonic distortion (THD)	0.01%
Leakageourrent(ICOM(OFF)/INO(OFF))	±20 nA
Power-supply current (I+)	0.1 μΑ
Package option	8-pin, DCT, DCU, YEP, or YZP



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



SCDS214 - OCTOBER 2005

ORDERING INFORMATION

TA	PACKAGE ⁽¹⁾		ORDERABLE PART NUMBER	TOP-SIDE MARKING ⁽²⁾
−40°C to 85°C	NanoStar™ – WCSP (DSBGA) 0.23-mm Large Bump – YEP	Town and made	TS5A3359YEPR	PDE///EW
	NanoFree™ – WCSP (DSBGA) 0.23-mm Large Bump – YZP (Pb-free)	Tape and reel	TS5A3359YZPR	PREVIEW
	SSOP - DCT	Tape and reel	TS5A3359DCTR	PREVIEW
	VSSOP - DCU	Tape and reel	TS5A3359DCUR	JAL_

⁽¹⁾ Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

Absolute Minimum and Maximum Ratings(1)(2)

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
٧+	Supply voltage range(3)		-0.5	6.5	V
V _{NO}	Analog voltage range(3)(4)(5)		-0.5	V ₊ + 0.5	V
ΙK	Analog port diode current	V _{NO} , V _{COM} < 0	-50		mA
I _{NO}	On-state switch current	V V 0. V	-200	200	
ICOM	On-state peak switch current(6)	V_{NO} , $V_{COM} = 0$ to V_{+}	-400	400	mA
VI	Digital input voltage range(3)(4)	•	-0.5	6.5	V
l _{IK}	Digital input clamp current	V _I < 0	-50		mA
I ₊	Continuous current through V+	•		100	
IGND	Continuous current through GND		-100	100	mA
	Dealers the section (7)	DCT/DCU package		227	2000
θ JA	Package thermal impedance(7)	YEP/YZP package		140	°C/W
T _{stg}	Storage temperature range	·	-65	150	°C

⁽¹⁾ Stresses above these ratings may cause permanent damage. Exposure to absolute maximum conditions for extended periods may degrade device reliability. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those specified is not implied.

⁽²⁾ DCT: The actual top-side marking has three additional characters that designate the year, month, and assembly/test site.

DCU: The actual top-side marking has one additional character that designates the assembly/test site.

YEP/YZP: The actual top-side marking has three preceding characters to denote year, month, and sequence code, and one following character to designate the assembly/test site. Pin 1 identifier indicates solder-bump composition (1 = SnPb, • = Pb-free).

⁽²⁾ The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum

⁽³⁾ All voltages are with respect to ground, unless otherwise specified.

⁽⁴⁾ The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

⁽⁵⁾ This value is limited to 5.5 V maximum.

⁽⁶⁾ Pulse at 1-ms duration < 10% duty cycle.

⁽⁷⁾ The package thermal impedance is calculated in accordance with JESD 51-7.



SCDS214 - OCTOBER 2005

Electrical Characteristics for 5-V Supply⁽¹⁾ $V_+ = 4.5 \text{ V}$ to 5.5 V, $T_A = -40^{\circ}\text{C}$ to 85°C (unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITIONS		TA	٧+	MIN	TYP	MAX	UNIT
Analog Switch				•					
Analog signal range	V _{COM} , V _{NO}					0		V ₊	V
Peak ON resistance	^r peak	$0 \le (V_{NO}) \le V_+,$ $I_{COM} = -100 \text{ mA},$	Switch ON, See Figure 13	25 °C Full	4.5 V		0.8	1.1 1.5	Ω
ON-state resistance	r _{on}	V _{NO} = 2.5 V, I _{COM} = -100 mA,	Switch ON, See Figure 13	25°C Full	4.5 V		0.7	0.9	Ω
ON-state resistance match between channels	Δr _{on}	$V_{NO} = 2.5 \text{ V},$ $I_{COM} = -100 \text{ mA},$	Switch ON, See Figure 13	25°C Full	4.5 V		0.1	0.1	Ω
ON-state		$0 \le (V_{NO}) \le V_{+},$ $I_{COM} = -100 \text{ mA},$	Switch ON, See Figure 13	25°C			0.15		
resistance flatness	^r on(flat)	V _{NO} = 1 V, 1.5 V, 2.5 V, I _{COM} = -100 mA,	Switch ON, See Figure 13	25°C Full	4.5 V		0.1	0.25 0.25	Ω
		$V_{NO} = 1 \text{ V}, V_{COM} = 1 \text{ V to } 4.5 \text{ V},$	Switch OFF,	25°C	5.5.1	-20	5	20	
NO OFF leakage	INO(OFF)	$V_{NO} = 4.5 \text{ V}, V_{COM} = 1 \text{ V to } 4.5 \text{ V},$	See Figure 14	Full	5.5 V	-150		150	nA
current	I _{NO(PWROFF)}	$V_{NO} = 0 \text{ to } 5.5 \text{ V},$ $V_{COM} = 5.5 \text{ V to } 0,$	Switch OFF, See Figure 14	25°C Full	0 V	-1 -25	0.8	25	μΑ
NO ON leakage	hioron	V _{NO} = 1 V, V _{COM} = Open,	Switch ON,	25°C	5.5 V	-30	5	30	nA
current	INO(ON)	V _{NO} = 4.5 V, V _{COM} = Open,	See Figure 15	Full	5.5 V	-220		220	IIA
0014	ICOM(OFF)	$V_{NO} = 4.5 \text{ V}, V_{COM} = 1 \text{ V to } 4.5 \text{ V},$	Switch OFF,	25°C	5.5 V	-25	8	25	nA
COM OFF leakage	'COM(OFF)	$V_{NO} = 1 \text{ V}, V_{COM} = 1 \text{ V to } 4.5 \text{ V},$	See Figure 14	Full	0.0 V	-250		250	ПА
current	COM(PWROFF)	$V_{COM} = 0 \text{ to } 5.5 \text{ V},$ $V_{NO} = 5.5 \text{ V to } 0,$	Switch OFF, See Figure 14	25°C Full	0 V	-8 -50	0.1	50 50	μΑ
COM		V _{NO} = Open, V _{COM} = 1 V,	Switch ON,	25°C		-30	5	30	
ON leakage current	ICOM(ON)	or $V_{NO} = Open, V_{COM} = 4.5 V,$	See Figure 15	Full	5.5 V	-220		220	nA
Digital Control Inpu	uts (IN1, IN2)(2)			•					
Input logic high	VIH			Full		2.4		5.5	V
Input logic low	V _{IL}			Full		0		0.8	V
Input leakage current	I _{IH} , I _{IL}	V _I = 5.5 V or 0		25°C Full	5.5 V	-2 -20		20	nA

⁽¹⁾ The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum

⁽²⁾ All unused digital inputs of the device must be held at V+ or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



SCDS214 - OCTOBER 2005

Electrical Characteristics for 5-V Supply⁽¹⁾ (continued) $V_+ = 4.5 \text{ V}$ to 5.5 V, $T_A = -40 ^{\circ}\text{C}$ to $85 ^{\circ}\text{C}$ (unless otherwise noted)

PARAMETER	SYMBOL	TEST COI	NDITIONS	TA	V ₊	MIN	TYP	MAX	UNIT
Dynamic									
Turn-on time	tON	V _{COM} = V ₊ ,	C _L = 35 pF,	25°C	5 V	1	2.5	21	ns
	¹ON	$R_L = 50 \Omega$,	See Figure 17	Full	4.5 V to 5.5 V	1		23.5	113
Turn-off time	^t OFF	$V_{COM} = V_+,$	$C_L = 35 \text{ pF},$	25°C	5 V	1	6	10.5	ns
	-011	$R_L = 50 \Omega$,	See Figure 17	Full	4.5 V to 5.5 V	1		12	
Break-before- make time	^t BBM	$V_{NO} = V_{+},$ $R_L = 50 \Omega,$	C _L = 35 pF, See Figure 18	25°C Full	5 V 4.5 V to 5.5 V	0.5 0.5	8.5	18 23	ns
Charge injection	QC	V _{GEN} = 0, R _{GEN} = 0,	C _L = 1 nF, See Figure 22	25°C	5 V		20		рС
NO OFF capacitance	C _{NO(OFF)}	V _{NO} = V ₊ or GND, Switch OFF,	See Figure 16	25°C	5 V		18		pF
COM OFF capacitance	CCOM(OFF)	V _{COM} = V ₊ or GND, Switch OFF,	See Figure 16	25°C	2.5 V		54		pF
NO ON capacitance	C _{NO(ON)}	V _{NO} = V ₊ or GND, Switch ON,	See Figure 16	25°C	5 V		78		pF
COM ON capacitance	C _{COM(ON)}	V _{COM} = V ₊ or GND, Switch ON,	See Figure 16	25°C	5 V		78		pF
Digital input capacitance	Cl	$V_I = V_+$ or GND,	See Figure 16	25°C	5 V		2.5		pF
Bandwidth	BW	$R_L = 50 \Omega$, Switch ON,	See Figure 19	25°C	5 V		75		MHz
OFF isolation	O _{ISO}	$R_L = 50 \Omega$, f = 1 MHz,	Switch OFF, See Figure 20	25°C	5 V		-64		dB
Crosstalk	X _{TALK}	$R_L = 50 \Omega$, f = 1 MHz,	Switch ON, See Figure 21	25°C	5 V		-64		dB
Total harmonic distortion	THD	$R_L = 600 \Omega$, $C_L = 50 pF$,	f = 20 Hz to 20 kHz, See Figure 23	25°C	5 V		0.005		%
Supply		ı		1	1				
Positive supply current	l ₊	$V_I = V_+ \text{ or GND},$	Switch ON or OFF	25°C Full	5.5 V		16	50 1200	nA

⁽¹⁾ The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum



SCDS214 - OCTOBER 2005

Electrical Characteristics for 3.3-V Supply⁽¹⁾ $V_+ = 3 \text{ V to } 3.6 \text{ V}, T_A = -40^{\circ}\text{C} \text{ to } 85^{\circ}\text{C} \text{ (unless otherwise noted)}$

PARAMETER	SYMBOL	TEST CONDITIONS		TA	٧+	MIN	TYP	MAX	UNIT
Analog Switch	•								
Analog signal range	V _{COM} , V _{NO} , V _{NC}					0		٧+	V
Peak ON resistance	r _{peak}	$0 \le (V_{NO}) \le V_{+},$ $I_{COM} = -100 \text{ mA},$	Switch ON, See Figure 13	25 °C Full	3 V		1.3	1.6	Ω
ON-state resistance	r _{on}	V _{NO} = 2 V, I _{COM} = -100 mA,	Switch ON, See Figure 13	25°C Full	3 V		1.2	1.6 1.8	Ω
ON-state resistance match between channels	Δr _{on}	V _{NO} = 2 V, 0.8 V, I _{COM} = -100 mA,	Switch ON, See Figure 13	25°C Full	3 V		0.1	0.15 0.15	Ω
ON-state		$0 \le (V_{NO}) \le V_{+},$ $I_{COM} = -100 \text{ mA},$	Switch ON, See Figure 13	25°C			0.2		
resistance flatness	ron(flat)	V _{NO} = 2 V, 0.8 V, I _{COM} = -100 mA,	Switch ON, See Figure 13	25°C Full	3 V		0.2	0.35 0.35	Ω
		$V_{NO} = 1 \text{ V}, V_{COM} = 1 \text{ V to 3 V},$	Switch OFF,	25°C		-15	3	15	
NO OFF leakage	INO(OFF)	or V _{NO} = 3 V, V _{COM} = 1 V to 3 V,	See Figure 14	Full	3.6 V	-30		30	nA
current	,	V _{NO} = 0 to 3.6 V,	Switch OFF,	25°C	0.1/	-1	0.2	1	^
	NO(PWROFF)	$V_{COM} = 3.6 \text{ V to } 0,$	See Figure 14	Full	0 V	-10		10	μΑ
NO ON leakage	hioroni	$V_{NO} = 1 V, V_{COM} = Open,$	Switch ON,	25°C	3.6 V	-15	3	15	nA
current	INO(ON)	V _{NO} = 3 V, V _{COM} = Open,	See Figure 15	Full	3.0 V	-40		40	IIA
		$V_{NO} = 0 \text{ V to } 3.6 \text{ V}, V_{COM} = 1 \text{ V},$	Switch OFF,	25°C	0.014	-15	3	15	
COM OFF leakage	ICOM(OFF)	or $V_{NO} = 3.6 \text{ V to 0 V}, V_{COM} = 3 \text{ V},$	See Figure 14	Full	3.6 V	-75		75	nA
current	loou and norm	$V_{COM} = 0$ to 3.6 V,	Switch OFF,	25°C	0 V	-1	0.2	1	μА
	COM(PWROFF)	$V_{NO} = 3.6 V \text{ to } 0,$	See Figure 14	Full	0 0	-20		20	μΑ
COM ON leakage	lagrygr	$V_{NO} = Open, V_{COM} = 1 V,$	Switch ON,	25°C	3.6 V	-15	4	15	nA
current	ICOM(ON)	$V_{NO} = Open, V_{COM} = 3 V,$	See Figure 15	Full	3.0 V	-40		40	IIA
Digital Control Inpu	uts (IN1, IN2) ⁽²⁾								
Input logic high	VIH			Full		2		5.5	V
Input logic low	V _{IL}			Full		0		8.0	V
Input leakage current	I _{IH} , I _{IL}	V _I = 5.5 V or 0		25°C Full	3.6 V	-2 -20		20	nA

⁽¹⁾ The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum

⁽²⁾ All unused digital inputs of the device must be held at V+ or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



SCDS214 - OCTOBER 2005

Electrical Characteristics for 3.3-V Supply⁽¹⁾ (continued) $V_+ = 3 \text{ V to } 3.6 \text{ V}, T_A = -40^{\circ}\text{C to } 85^{\circ}\text{C (unless otherwise noted)}$

PARAMETER	SYMBOL	TEST CO	NDITIONS	TA	٧+	MIN	TYP	MAX	UNIT
Dynamic	•								
Turn-on time	ton	V _{COM} = V ₊ ,	C _L = 35 pF,	25°C	3.3 V	1	16	30.5	ns
	0.11	$R_L = 50 \Omega$,	See Figure 17	Full	3 V to 3.6 V	1		34	
Turn-off time	tOFF	$V_{COM} = V_+,$ $R_L = 50 \Omega,$	C _L = 35 pF, See Figure 17	25°C Full	3.3 V 3 V to 3.6 V	1	6	11.5	ns
Break-before-		$V_{NC} = V_{NO} = V_{+}$	C _I = 35 pF,	25°C	3.3 V	0.5	13	26	
make time	^t BBM	$R_L = 50 \Omega$	See Figure 18	Full	3 V to 3.6 V	0.5		30	ns
Charge injection	QC	V _{GEN} = 0, R _{GEN} = 0,	C _L = 1 nF, See Figure 22	25°C	3.3 V		12		pC
NO OFF capacitance	C _{NO(OFF)}	V _{NO} = V ₊ or GND, Switch OFF,	See Figure 16	25°C	3.3 V		18		pF
COM OFF capacitance	CCOM(OFF)	V _{COM} = V ₊ or GND, Switch OFF,	See Figure 16	25°C	3.3 V		55		pF
NO ON capacitance	C _{NO(ON)}	V _{NO} = V ₊ or GND, Switch ON,	See Figure 16	25°C	3.3 V		78		pF
COM ON capacitance	CCOM(ON)	V _{COM} = V ₊ or GND, Switch ON,	See Figure 16	25°C	3.3 V		78		pF
Digital input capacitance	Cl	$V_I = V_+ \text{ or GND},$	See Figure 16	25°C	3.3 V		2.5		pF
Bandwidth	BW	$R_L = 50 \Omega$, Switch ON,	See Figure 19	25°C	3.3 V		73		MHz
OFF isolation	O _{ISO}	$R_L = 50 \Omega$, f = 1 MHz,	Switch OFF, See Figure 20	25°C	3.3 V		-64		dB
Crosstalk	XTALK	$R_L = 50 \Omega$, f = 1 MHz,	Switch ON, See Figure 21	25°C	3.3 V		-64		dB
Total harmonic distortion	THD	$R_L = 600 \Omega$, $C_L = 50 pF$,	f = 20 Hz to 20 kHz, See Figure 23	25°C	3.3 V		0.010		%
Supply	·				•				
Positive supply current	I ₊	$V_I = V_+ \text{ or GND},$	Switch ON or OFF	25°C Full	3.6 V		2	20 350	nA

⁽¹⁾ The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum



SCDS214 - OCTOBER 2005

Electrical Characteristics for 2.5-V Supply⁽¹⁾ $V_+ = 2.3 \text{ V to } 2.7 \text{ V, } T_A = -40 ^{\circ}\text{C} \text{ to } 85 ^{\circ}\text{C} \text{ (unless otherwise noted)}$

PARAMETER	SYMBOL	TEST CONDITIONS		TA	٧+	MIN	TYP	MAX	UNIT
Analog Switch									
Analog signal range	V _{COM} , V _{NO}					0		٧+	V
Peak ON resistance	r _{peak}	$0 \le (V_{NO}) \le V_+,$ $I_{COM} = -8 \text{ mA},$	Switch ON, See Figure 13	25 °C Full	2.3 V		1.8	2.5	Ω
ON-state resistance	r _{on}	V _{NO} = 1.8 V, I _{COM} = -8 mA,	Switch ON, See Figure 13	25°C Full	2.3 V		1.5	2.4	Ω
ON-state resistance	4-	V _{NO} = 1.8 V,	Switch ON,	25°C	227		0.15	0.2	0
match between channels	∆r _{on}	$I_{COM} = -8 \text{ mA},$	See Figure 13	Full	2.3 V			0.2	Ω
ON-state	_	$0 \le (V_{NO}) \le V_+,$ $I_{COM} = -8 \text{ mA},$	Switch ON, See Figure 13	25°C	001/		0.6		0
resistance flatness	^r on(flat)	$V_{NO} = 0.8 \text{ V}, 1.8 \text{ V},$ $I_{COM} = -8 \text{ mA},$	Switch ON, See Figure 13	25°C Full	2.3 V		0.6	1	Ω
		$V_{NO} = 0.5 \text{ V}, V_{COM} = 0.5 \text{ V to } 2.3 \text{ V},$	Switch OFF,	25°C	0.71/	-15	3	15	
NO OFF leakage	INO(OFF)	or $V_{NO} = 2.3 \text{ V}, V_{COM} = 0.5 \text{ V} \text{ to } 2.3 \text{ V},$	See Figure 14	Full	2.7 V	-30		30	nA
current	INO(PWROFF)	$V_{NO} = 0 \text{ to } 2.7 \text{ V},$ $V_{COM} = 2.7 \text{ V to } 0,$	Switch OFF, See Figure 14	25°C Full	0 V	-1 -10	0.1	10	μΑ
NO		$V_{NO} = 0.5 \text{ V}, V_{COM} = \text{Open},$	Switch ON,	25°C		-15	3	15	
ON leakage current	INO(ON)	or $V_{NO} = 2.2 \text{ V}, V_{COM} = \text{Open},$	See Figure 15	Full	2.7 V	-35		35	nA
	loovyour)	$V_{NO} = 0.3 \text{ V to } 2.3 \text{ V, } V_{COM} = 0.5 \text{ V,}$	Switch OFF,	25°C	2.7 V	-15	3	15	nA
COM OFF leakage	ICOM(OFF)	$V_{NO} = 0.3 \text{ V to } 2.3 \text{ V, } V_{COM} = 2.3 \text{ V,}$	See Figure 14	Full	2.7 V	-60		60	ПА
current	COM(PWROFF)	$V_{COM} = 0 \text{ to } 2.7 \text{ V},$ $V_{NO} = 2.7 \text{ V to } 0,$	Switch OFF, See Figure 14	25°C	0 V	-1	0.1	1	μΑ
COM	,	$V_{NO} = Open, V_{COM} = 0.5 V,$		Full 25°C		-10 -15	3.5	10	
ON leakage current	I _{COM(ON)}	or V _{NO} = Open V, V _{COM} = 2.2 V,	Switch ON, See Figure 15	Full	2.7 V	-40		40	nA
	Inputs (IN1, IN2								
Input logic high	VIH			Full		1.8		5.5	V
Input logic low	V _{IL}			Full		0		0.6	V
Input leakage current	l _{IH} , l _{IL}	V _I = 5.5 V or 0		25°C Full	2.7 V	1 10		10	nA

⁽¹⁾ The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum

⁽²⁾ All unused digital inputs of the device must be held at V₊ or GND to ensure proper device operation. Refer to the TI application report, *Implications* of Slow or Floating CMOS Inputs, literature number SCBA004.



SCDS214 - OCTOBER 2005

Electrical Characteristics for 2.5-V Supply⁽¹⁾ (continued) $V_+ = 2.3 \text{ V}$ to 2.7 V, $T_A = -40 ^{\circ}\text{C}$ to 85°C (unless otherwise noted)

PARAMETER	SYMBOL	TEST CO	NDITIONS	TA	٧+	MIN	TYP	MAX	UNIT
Dynamic					-				
Turn-on time		V _{COM} = V ₊ ,	C _L = 35 pF,	25°C	2.5 V	2	4.5	43	
rum-on time	tON	$R_L = 50 \Omega$,	See Figure 17	Full	2.3 V to 2.7 V	2		47.5	ns
Turn-off time	torr	$V_{COM} = V_+,$	$C_L = 35 pF$,	25°C	2.5 V	2	8.5	11	ns
Tarri on time	tOFF	$R_L = 50 \Omega$,	See Figure 17	Full	2.3 V to 2.7 V	2		12.5	113
Break-before-	tooM	$V_{NO} = V_{+}$	$C_L = 35 pF$,	25°C	2.5 V	0.5	18.5	38.5	ns
make time	^t BBM	$R_L = 50 \Omega$,	See Figure 18	Full	2.3 V to 2.7 V	0.5		43	113
Charge injection	QC	V _{GEN} = 0, R _{GEN} = 0,	$C_L = 1 \text{ nF},$ See Figure 22	25°C	2.5 V		8		рС
NO OFF capacitance	C _{NO(OFF)}	V _{NO} = V ₊ or GND, Switch OFF,	See Figure 16	25°C	2.5 V		18.5		pF
COM OFF capacitance	CCOM(OFF)	V _{COM} = V ₊ or GND, Switch OFF,	See Figure 16	25°C	2.5 V		55		pF
NO ON capacitance	C _{NO(ON)}	V _{NO} = V ₊ or GND, Switch ON,	See Figure 16	25°C	2.5 V		78		pF
COM ON capacitance	C _{COM} (ON)	V _{COM} = V ₊ or GND, Switch ON,	See Figure 16	25°C	2.5 V		78		pF
Digital input capacitance	Cl	$V_I = V_+ \text{ or GND},$	See Figure 16	25°C	2.5 V		3		pF
Bandwidth	BW	$R_L = 50 \Omega$, Switch ON,	See Figure 19	25°C	2.5 V		73		MHz
OFF isolation	O _{ISO}	$R_L = 50 \Omega$, f = 1 MHz,	Switch OFF, See Figure 20	25°C	2.5 V		-64		dB
Crosstalk	XTALK	$R_L = 50 \Omega$, f = 1 MHz,	Switch ON, See Figure 21	25°C	2.5 V		-64		dB
Total harmonic distortion	THD	$R_L = 600 \Omega$, $C_L = 50 pF$,	f = 20 Hz to 20 kHz, See Figure 23	25°C	2.5 V		0.030		%
Supply		•			•				
Positive supply		V V 0ND	0 % 1 0 11 0 2 ==	25°C	0.71/		1	10	
current	1+	$V_I = V_+ \text{ or GND},$	Switch ON or OFF	Full	2.7 V			250	nA

⁽¹⁾ The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum



SCDS214 - OCTOBER 2005

Electrical Characteristics for 1.8-V Supply⁽¹⁾ $V_+ = 1.65 \text{ V}$ to 1.95 V, $T_A = -40 ^{\circ}\text{C}$ to $85 ^{\circ}\text{C}$ (unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITIONS		T_{A}	٧+	MIN	TYP	MAX	UNIT
Analog Switch					•				
Analog signal range	VCOM, VNO								V
Peak ON resistance	^r peak	$0 \le (V_{NO}) \le V_+,$ $I_{COM} = -2 \text{ mA},$	Switch ON, See Figure 13	25 °C Full	1.65 V		5	30	Ω
ON-state resistance	r _{on}	V _{NO} = 1.5 V, I _{COM} = -2 mA,	Switch ON, See Figure 13	25°C Full	1.65 V		2	2.5 3.5	Ω
ON-state resistance		V _{NO} = 1.5 V,	Switch ON,	25°C			0.15	0.4	
match between channels	∆r _{on}	$I_{COM} = -2 \text{ mA},$	See Figure 13	Full	1.65 V			0.4	Ω
ON-state		$0 \le (V_{NO}) \le V_+,$ $I_{COM} = -2 \text{ mA},$	Switch ON, See Figure 13	25°C	4.05.1/		5		0
resistance flatness	ron(flat)	$V_{NO} = 0.6 \text{ V}, 1.5 \text{ V},$ $I_{COM} = -2 \text{ mA},$	Switch ON, See Figure 13	25°C Full	1.65 V		4.5	TBD TBD	Ω
		$V_{NO} = 0.3 \text{ V}, V_{COM} = 0.3 \text{ V to } 1.65 \text{ V},$	Switch OFF,	25°C	4.05.1/	-15	3	15	
NO OFF leakage	INO(OFF)	or V _{NO} = 1.65 V, V _{COM} = 0.3 V to 1.65 V, See Figure 14	Full	1.95 V	-30		30	nA	
current	INO(PWROFF)	V _{NO} = 0 to 1.95 V,	Switch OFF,	25°C	0 V	-1	0.1	1	μA
NO	TIO(I VIII (OI I)	V _{COM} = 1.95 V to 0,	See Figure 14	Full		-15		15	•
ON leakage current	I _{NO(ON)}	$V_{NO} = 0.3 \text{ V, } V_{COM} = \text{Open,}$ or $V_{NO} = 1.65 \text{ V, } V_{COM} = \text{Open,}$	Switch ON, See Figure 15	25°C Full	1.95 V	-15 -30	3	15 30	nA
		$V_{NO} = 0.3 \text{ V to } 1.65 \text{ V}, V_{COM} = 0.3 \text{ V},$	Switch OFF,	25°C		-15	3	15	
COM OFF leakage	ICOM(OFF)	or $V_{NO} = 0.3 \text{ V to } 1.65 \text{ V}, V_{COM} = 1.65 \text{ V},$	See Figure 14	Full	1.95 V	-50		50	nA
current	COM(PWROFF)	V _{COM} = 0 to 1.95 V,	Switch OFF,	25°C	0 V	-1	0.1	1	μА
	*CON(PVIKOFF)	V _{NO} = 1.95 V to 0,	See Figure 14	Full		-10		10	μ
COM ON leakage	ICOM(ON)	$V_{NO} = Open, V_{COM} = 0.3 V,$	Switch ON,	25°C	1.95 V	-15	3	15	nA
current	, ,	V _{NO} = Open, V _{COM} = 1.65 V,	See Figure 15	Full		-30		30	
	Inputs (IN1, IN2	y(2)		1	- I				
Input logic high	VIH			Full		1.5		5.5	V
Input logic low	V _{IL}			Full		0		0.6	V
Input leakage current	liH, li⊏	V _I = 5.5 V or 0		25°C Full	1.95 V	-2 20		20	nA

⁽¹⁾ The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum

⁽²⁾ All unused digital inputs of the device must be held at V₊ or GND to ensure proper device operation. Refer to the TI application report, *Implications* of Slow or Floating CMOS Inputs, literature number SCBA004.



SCDS214 - OCTOBER 2005

Electrical Characteristics for 1.8-V Supply⁽¹⁾ (continued) $V_+ = 1.65 \text{ V}$ to 1.95 V, $T_A = -40 ^{\circ}\text{C}$ to 85°C (unless otherwise noted)

PARAMETER	SYMBOL	TEST CO	NDITIONS	TA	V ₊	MIN	TYP	MAX	UNIT
Dynamic	•								
Turn-on time	4	V _{COM} = V ₊ ,	C _L = 35 pF,	25°C	1.8 V	3	38.5	85	
rum-on time	tON	$R_L = 50 \Omega$,	See Figure 17	Full	1.65 V to 1.95 V	3		90	ns
Turn-off time	torr	$V_{COM} = V_+,$	$C_L = 35 pF$,	25°C	1.8 V	2	8.5	16	ns
Turr on time	tOFF	$R_L = 50 \Omega$,	See Figure 17	Full	1.65 V to 1.95 V	2		18	113
Break-before-	t _{BBM}	V _{NO} = V ₊ ,	$C_L = 35 \text{ pF},$	25°C	1.8 V	1	33	75	ns
make time	-DDIVI	$R_L = 50 \Omega$,	See Figure 18	Full	1.65 V to 1.95 V	1		80	
Charge injection	QC	V _{GEN} = 0, R _{GEN} = 0,	$C_L = 1 \text{ nF},$ See Figure 22	25°C	1.8 V		5		рС
NO OFF capacitance	C _{NO(OFF)}	V _{NO} = V ₊ or GND, Switch OFF,	See Figure 16	25°C	1.8 V		18.5		pF
COM OFF capacitance	CCOM(OFF)	V _{COM} = V ₊ or GND, Switch OFF,	See Figure 16	25°C	1.8 V		55		рF
NO ON capacitance	C _{NO(ON)}	$V_{NO} = V_{+}$ or GND, Switch ON,	See Figure 16	25°C	1.8 V		78		рF
COM ON capacitance	C _{COM(ON)}	V _{COM} = V ₊ or GND, Switch ON,	See Figure 16	25°C	1.8 V		78		рF
Digital input capacitance	Cl	$V_I = V_+$ or GND,	See Figure 16	25°C	1.8 V		3		pF
Bandwidth	BW	$R_L = 50 \Omega$, Switch ON,	See Figure 19	25°C	1.8 V		73		MHz
OFF isolation	O _{ISO}	$R_L = 50 \Omega$, f = 1 MHz,	Switch OFF, See Figure 20	25°C	1.8 V		-64		dB
Crosstalk	X _{TALK}	$R_L = 50 \Omega$, f = 1 MHz,	Switch ON, See Figure 21	25°C	1.8 V		-64		dB
Total harmonic distortion	THD	$R_L = 600 \Omega$, $C_L = 50 pF$,	f = 20 Hz to 20 kHz, See Figure 23	25°C	1.8 V		0.080		%
Supply		ı							•
Positive supply current	l ₊	$V_I = V_+$ or GND,	Switch ON or OFF	25°C Full	1.95 V		1	200	nA

⁽¹⁾ The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum



TYPICAL PERFORMANCE

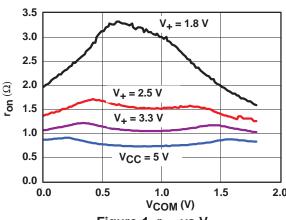
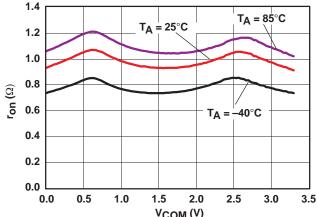


Figure 1. ron vs V_{COM}



 $V_{COM}(V)$ Figure 2. r_{on} vs $V_{COM}(V_{+} = 3.3 \text{ V})$

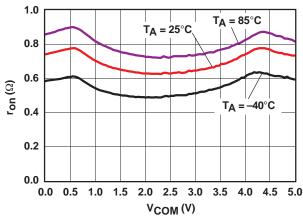


Figure 3. r_{on} vs V_{COM} ($V_{+} = 5 V$)

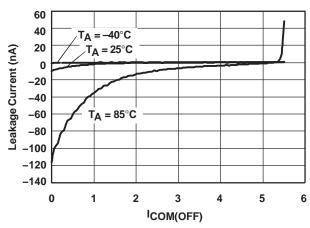


Figure 4. Leakage Current vs Temperature

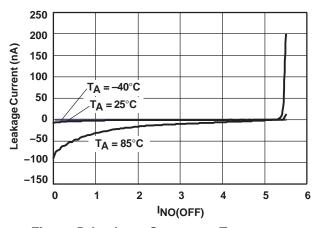


Figure 5. Leakage Current vs Temperature

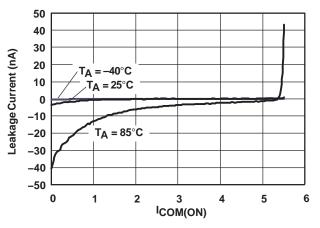


Figure 6. Leakage Current vs Temperature



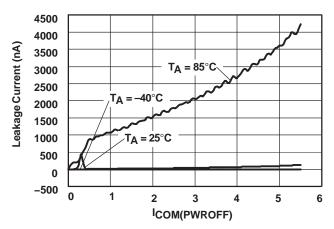


Figure 7. Leakage Current vs Temperature

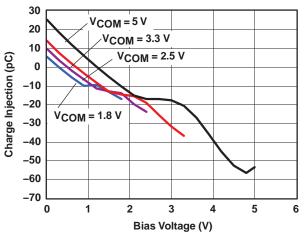


Figure 8. Charge Injection (Q_C) vs V_{COM}

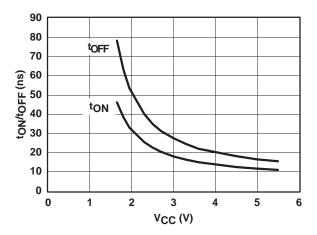


Figure 9. toN and toFF vs Supply Voltage

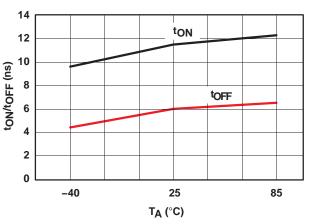


Figure 10. t_{ON} and t_{OFF} vs Temperature

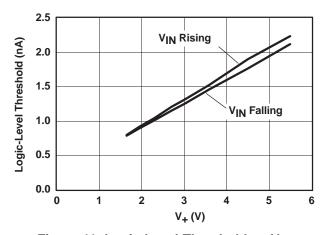


Figure 11. Logic-Level Threshold vs V₊

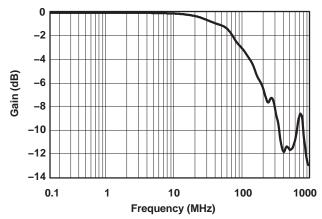
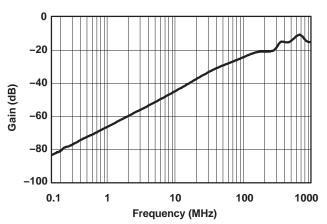


Figure 12. Bandwidth $(V_+ = 5 V)$



0.010 0.009 0.008 0.007 0.006 THD (%) 0.005 0.004 0.003 0.002 0.001 0.000 0.01 10 0.1 1 100 Frequency (kHz)

Figure 13. OFF Isolation vs Crosstalk

Figure 14. Total Harmonic Distortion vs Frequency

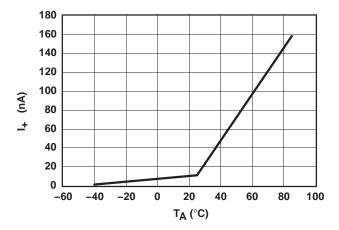


Figure 15. Power-Supply Current vs Temperature $(V_+ = 5 V)$



PIN DESCRIPTION

PIN NUMBER	NAME	DESCRIPTION
1	NO0	Digital control pin to connect COM to NO
2	NO1	Normally open
3	NO2	Normally open
4	GND	Digital ground
5	IN2	Digital control pin to connect COM to NO
6	IN1	Digital control pin to connect COM to NO
7	СОМ	Common
8	V ₊	Power supply

PARAMETER DESCRIPTION

SYMBOL	DESCRIPTION
VCOM	Voltage at COM
V _{NO}	Voltage at NO
r _{on}	Resistance between COM and NO ports when the channel is ON
^r peak	Peak on-state resistance over a specified voltage range
$\Delta r_{ extsf{on}}$	Difference of ron between channels in a specific device
ron(flat)	Difference between the maximum and minimum value of ron in a channel over the specified range of conditions
I _{NO(OFF)}	Leakage current measured at the NO port, with the corresponding channel (NO to COM) in the OFF state under worst-case input and output conditions
INO(PWROFF)	Leakage current measured at the NO port during the power-down condition, $V_{+} = 0$
I _{NO(ON)}	Leakage current measured at the NO port, with the corresponding channel (NO to COM) in the ON state and the output (COM) open
ICOM(ON)	Leakage current measured at the COM port, with the corresponding channel (COM to NO) in the ON state and the output (NO) open
ICOM(OFF)	Leakage current measured at the COM port, with the corresponding channel (COM to NC) in the OFF state under worst-case input and output conditions
COM(PWROFF)	Leakage current measured at the COM port during the power-down condition, $V_{+} = 0$
VIH	Minimum input voltage for logic high for the control input (IN)
V _{IL}	Maximum input voltage for logic low for the control input (IN)
VI	Voltage at the control input (IN)
I _{IH} , I _{IL}	Leakage current measured at the control input (IN)
tON	Turn-on time for the switch. This parameter is measured under the specified range of conditions and by the propagation delay between the digital control (IN) signal and analog output (COM, or NO) signal when the switch is turning ON.
^t OFF	Turn-off time for the switch. This parameter is measured under the specified range of conditions and by the propagation delay between the digital control (IN) signal and analog output (COM, or NO) signal when the switch is turning OFF.
^t BBM	Break-before-make time. This parameter is measured under the specified range of conditions and by the propagation delay between the output of two adjacent analog channels (NC and NO) when the control signal changes state.
QC	Charge injection is a measurement of unwanted signal coupling from the control (IN) input to the analog (NO, or COM) output. This is measured in coulomb (C) and measured by the total charge induced due to switching of the control input. Charge injection, $Q_C = C_L \times \Delta V_{COM}$, C_L is the load capacitance, and ΔV_{COM} is the change in analog output voltage.



SCDS214 - OCTOBER 2005

PARAMETER DESCRIPTION (continued)

SYMBOL	DESCRIPTION
C _{NO(OFF)}	Capacitance at the NO port when the corresponding channel (NO to COM) is OFF
C _{NO(ON)}	Capacitance at the NO port when the corresponding channel (NO to COM) is ON
C _{COM(ON)}	Capacitance at the COM port when the corresponding channel (COM to NO) is ON
C _{COM(OFF)}	Capacitance at the COM port when the corresponding channel (COM to NO) is OFF
Cl	Capacitance of control input (IN)
O _{ISO}	OFF isolation of the switch is a measurement of OFF-state switch impedance. This is measured in dB in a specific frequency, with the corresponding channel (NO to COM) in the OFF state.
X _{TALK}	Crosstalk is a measurement of unwanted signal coupling from an ON channel to an OFF channel (NC to NO or NO to NC). This is measured in a specific frequency and in dB.
BW	Bandwidth of the switch. This is the frequency in which the gain of an ON channel is -3 dB below the DC gain.
THD	Total harmonic distortion describes the signal distortion caused by the analog switch. This is defined as the ratio of root mean square (RMS) value of the second, third, and higher harmonic to the absolute magnitude of the fundamental harmonic.
l ₊	Static power-supply current with the control (IN) pin at V ₊ or GND



PARAMETER MEASUREMENT INFORMATION

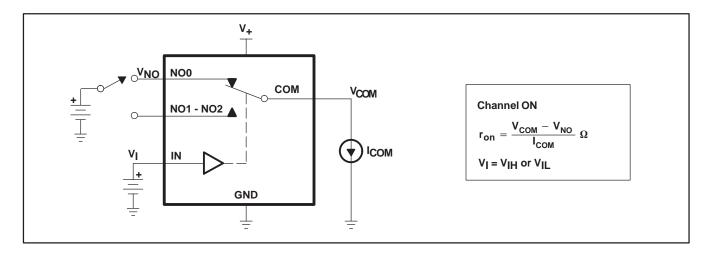
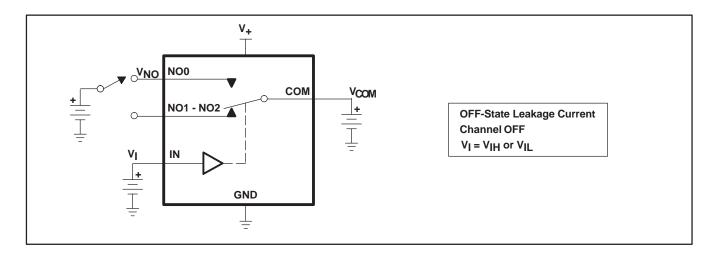


Figure 16. ON-State Resistance (ron)



 $Figure~17.~OFF-State~Leakage~Current~(I_{NC(OFF)},~I_{NO(OFF)},~I_{NO(PWROFF)},~I_{COM(OFF)},~I_{COM(PWROFF)})\\$

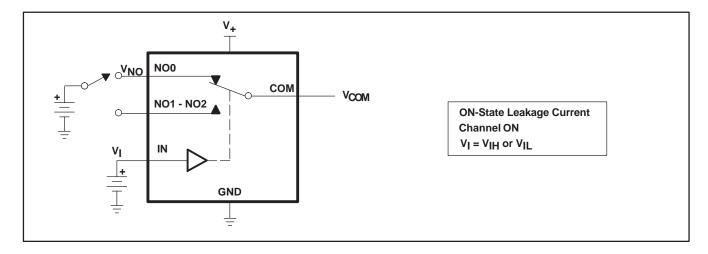


Figure 18. ON-State Leakage Current ($I_{COM(ON)}$, $I_{NO(ON)}$)

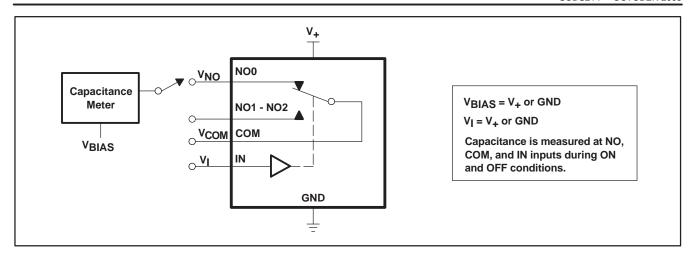
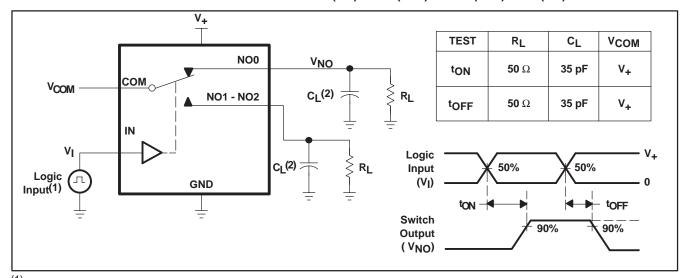


Figure 19. Capacitance (C_I, C_{COM(ON)}, C_{NO(OFF)}, C_{COM(OFF)}, C_{NO(ON)})

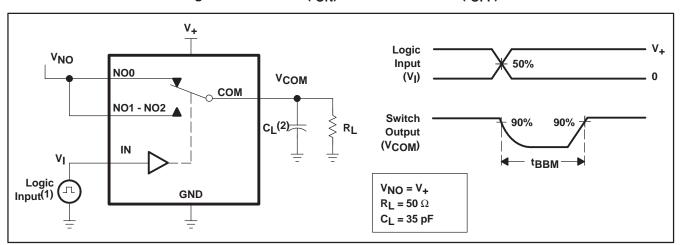


- (1) All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \Omega$, $t_f < 5 \text{ ns}$, $t_f < 5 \text{ ns}$.
- (2) C₁ includes probe and jig capacitance.

STRUMENTS

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Figure 20. Turn-On (t_{ON}) and Turn-Off Time (t_{OFF})



⁽¹⁾ All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_Ω = 50 Ω, t_f < 5 ns, t_f < 5 ns.

(2) C_I includes probe and jig capacitance.

Figure 21. Break-Before-Make Time (t_{BBM})



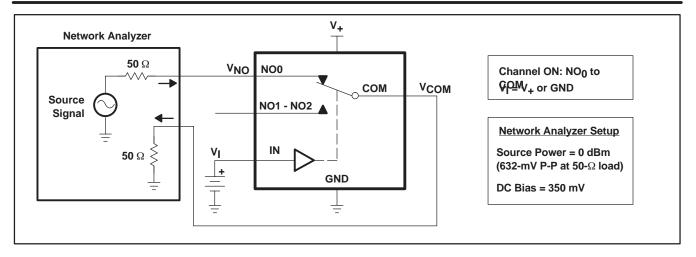


Figure 22. Bandwidth (BW)

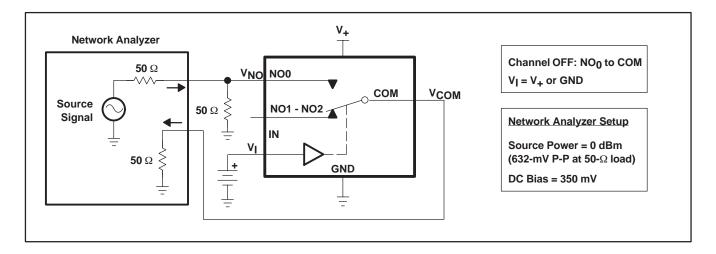


Figure 23. OFF Isolation (O_{ISO})

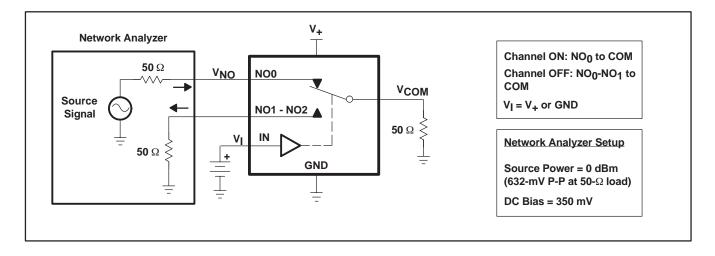
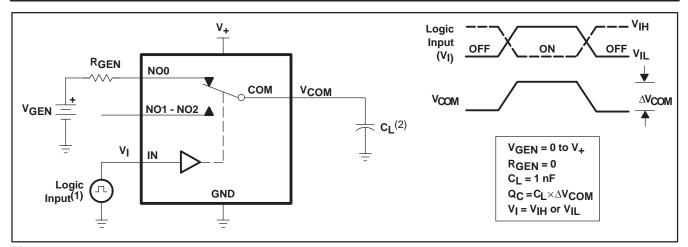
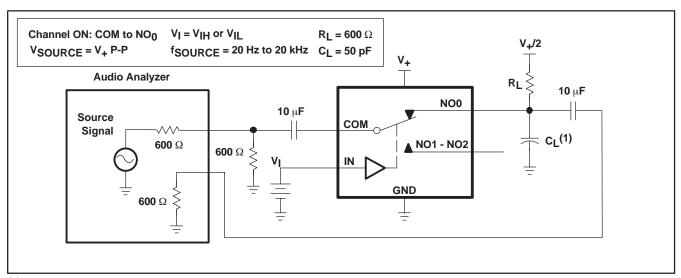


Figure 24. Crosstalk (X_{TALK})



- (1) All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \Omega$, $t_f < 5 \text{ ns}$, $t_f < 5 \text{ ns}$.
- (2) C_L includes probe and jig capacitance.

Figure 25. Charge Injection (Q_C)



(1) C_L includes probe and jig capacitance.

Figure 26. Total Harmonic Distortion (THD)





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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
TS5A3359DCUR	ACTIVE	US8	DCU	8	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TS5A3359DCURE4	ACTIVE	US8	DCU	8	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TS5A3359DCUT	ACTIVE	US8	DCU	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TS5A3359DCUTE4	ACTIVE	US8	DCU	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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DCU (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE (DIE DOWN)



NOTES:

- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
 - D. Falls within JEDEC MO-187 variation CA.



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